LOW-PROFILE BLADE AND BEAM



(0.50 mm) .0197" PITCH • LTH/LSH SERIES

LTH Mates: LSH

LSH Mates:

NO. OF POSITIONS LTH **PER ROW**

-010, -020,

-030, -040, -050

01

PLATING OPTION

-G

= 10 µ"

(0.25 µm) Gold

(1.68)

066

(5.05)



OPTION

-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad

-TR = Tape & Reel

-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

-K = (7.50 mm) .295" DIA

Polyimide film Pick & Place Pad

-TR

= Tape & Reel

-FR = Full Reel Tape & Reel

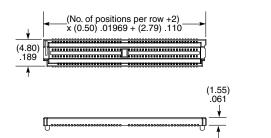
SPECIFICATIONS

Insulator Material: Liquid Crystal Polymer Terminal Material: Phosphor Bronze Contact Material:

Plating: Au over 50 μ" (1.27 μm) Ni Current Rating: 2.6 A per pin (2 pins powered) Operating Temp Range: -55 °C to +125 °C

PROCESSING

Yes SMT Lead Coplanarity: (0.10 mm) .004" max Board Stacking:



Lead-Free Solderable:

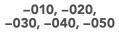
For applications requiring more than two connectors per board, contact ipg@samtec.com



MATED HEIGHT

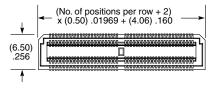
LEAD STYLE MATED HEIGHT* (2.31 mm) .091"

*Processing conditions will affect mated height.



-G = 10 µ" (0.25 µm)

OPTION







(6.73)

Note:

Some lengths, styles and options are non-standard, non-returnable.